

## Ultra Low Capacitance ESD Protection Array

### DESCRIPTION

GESD0512T5L is an ultra-low capacitance ESD Protection Array with typical capacitance of 0.20pF (I/O to I/O) only, GESD0512T5L is designed to protect parasitic-sensitive systems against over-voltage and over-current transient events. It complies with IEC 61000-4-2 (ESD), Level 4(±15KV air, ±8KV contact discharge), IEC61000-4-4 (electrical fast transient-EFT) (40A, 5/50ns), very fast charged device model (CDM) ESD and cable discharge event (CDE), etc.

GESD0512T5L uses small SOT-563 package. Each GESD0512T5L device can protect two high-speed data lines and one Vcc line. The combined features of ultra-low capacitance, small size and high ESD robustness make GESD0512T5L ideal for high-speed data ports and high-frequency lines (e.g., HDMI & DVI) applications. The low clamping voltage of the GESD0512T5L guarantees a minimum stress on the protected IC.

### ORDERING INFORMATION

- ✧ Device: GESD0512T5L
- ✧ Package: SOT-563
- ✧ Marking: F
- ✧ Material: Halogen free and RoHS compliant
- ✧ Packing: Tape & Reel
- ✧ Quantity per reel: 3,000pcs

### FEATURES

- ✧ Transient protection for high-speed data lines  
IEC 61000-4-2(ESD) ±20KV(Contact)  
IEC 61000-4-2(ESD) ±25KV(Air)
- ✧ Package optimized for high-speed lines
- ✧ Small package(2.9mm\*2.8mm\*1.1mm)
- ✧ Protects two data lines and one Vcc line
- ✧ Low capacitance: 0.20pF (I/O to I/O)
- ✧ Low leakage current
- ✧ Low clamping voltage
- ✧ Each I/O pin can withstand over 1000 ESD strikes for ±8KV contact discharge

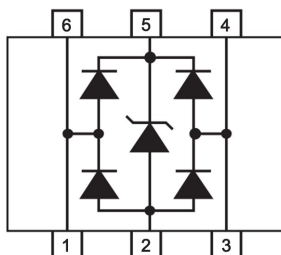
### MACHANICAL DATA

- ✧ SOT-563 package
- ✧ Flammability Rating: UL 94V-0
- ✧ Terminal: Matte tin plated.
- ✧ High temperature soldering guaranteed:  
✧ 260°C/10s
- ✧ Packaging: Tape and Reel
- ✧ Reel size: 7 inch

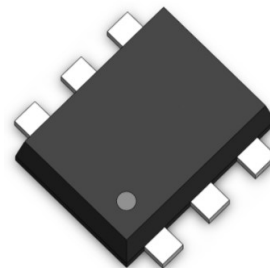
### APPLICATIONS

- ✧ Serial ATA
- ✧ MDDI Ports
- ✧ USB 2.0/3.0 Power and Data Line Protection
- ✧ Display Ports
- ✧ High Definition Multi-Media Interface (HDMI)
- ✧ Digital Visual Interface (DVI)

### PIN CONFIGURATION



### PACKAGE OUTLINE



### ABSOLUTE MAXIMUM RATING

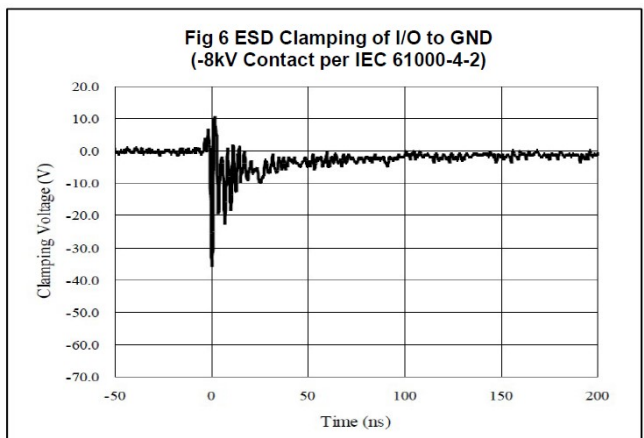
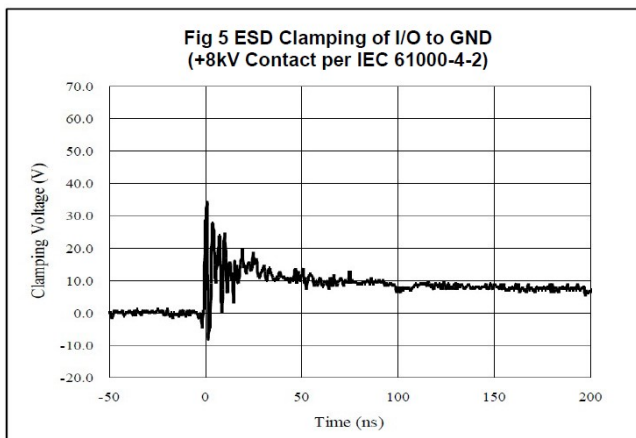
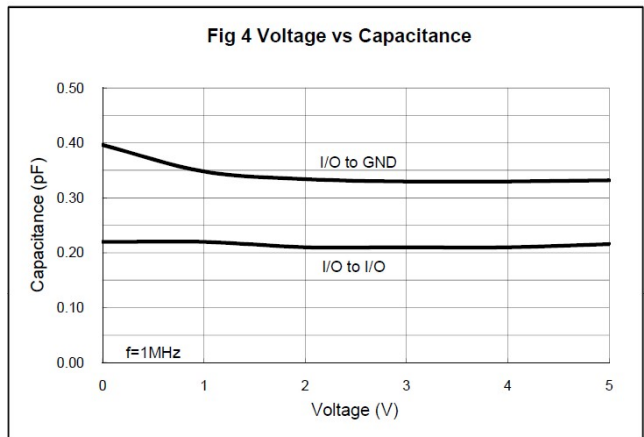
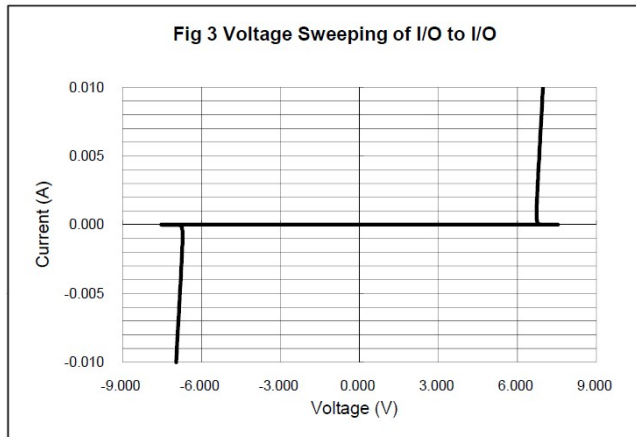
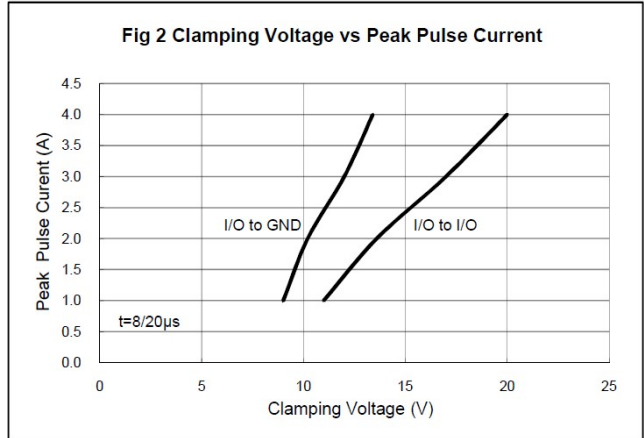
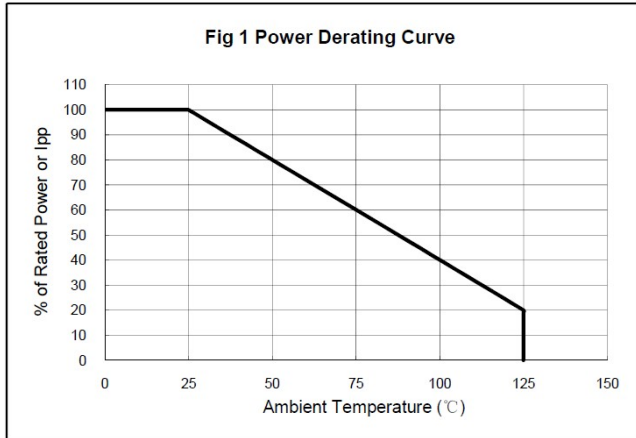
Symbol	Parameter	Value	Units
$P_{PP}$	Peak Pulse Power (8/20 $\mu$ s)	60	W
$V_{ESD}$	ESD per IEC 61000-4-2 (Contact) ESD per IEC 61000-4-2 (Air)	$\pm 20$ $\pm 25$	kV
$T_{OPT}$	Operating Temperature	-55/+125	$^{\circ}$ C
$T_{STG}$	Storage Temperature	-55/+150	$^{\circ}$ C

### ELECTRICAL CHARACTERISTICS (Tamb=25 $^{\circ}$ C)

Symbol	Parameter	Test Condition	Min	Typ	Max	Units
$V_{RWM}$	Reverse Working Voltage	Any I/O pin to GND			5.0	V
$V_{BR}$	Reverse Breakdown Voltage	$I_T = 1\text{mA}$ Any I/O pin to GND	6.0		9.0	V
$I_R$	Reverse Leakage Current	$V_{RWM} = 5\text{V}$ Any I/O pin to GND			1.0	$\mu$ A
$V_C$	Clamping Voltage	$I_{PP} = 1\text{A}$ , $t_p = 8/20\mu\text{s}$ Any I/O pin to GND			10	V
		$I_{PP} = 4\text{A}$ , $t_p = 8/20\mu\text{s}$ Any I/O pin to GND			15	V
		$I_{PP} = 8\text{A}$ , $t_p = 8/20\mu\text{s}$ Vcc pin to GND			15	V
$C_{ESD}$	Parasitic Capacitance	$V_R = 0\text{V}$ , $f = 1\text{MHz}$ Between I/O and I/O		0.20	0.30	pF
		$V_R = 0\text{V}$ , $f = 1\text{MHz}$ Between I/O and GND		0.45	0.50	pF
		$V_R = 0\text{V}$ , $f = 1\text{MHz}$ Between Vcc and GND		0.80		pF

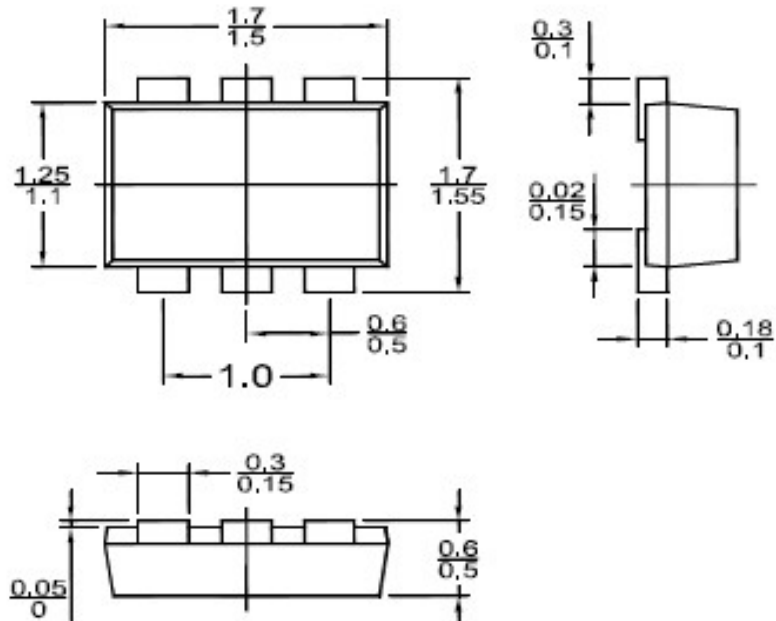
Note: I/O Pins are Pin 1,3,4,6. Pin 5 is Vcc. Pin 2 is GND.

### ELECTRICAL CHARACTERISTICS CURVE



## SOT-563 PACKAGE OUTLINE DIMENSIONS

Package Outline Dimensions (Units: mm)



Recommended Soldering Footprint

